

University of Nebraska - Lincoln

DigitalCommons@University of Nebraska - Lincoln

Theses, Dissertations, and Student Research from
Electrical & Computer Engineering

Electrical & Computer Engineering, Department of

4-2017

Reducing Graphene-Metal Contact Resistance via Laser Nano-welding

Kamran Keramatnejad

University of Nebraska-Lincoln, k.keramatnejad@huskers.unl.edu

H. Rabiee Golgir

University of Nebraska-Lincoln, rabiee@huskers.unl.edu

Y. S. Zhou

University of Nebraska-Lincoln

D. W. Li

University of Nebraska-Lincoln, dli8@unl.edu

X. Huang

University of Nebraska-Lincoln

See next page for additional authors

Follow this and additional works at: <http://digitalcommons.unl.edu/elecengtheses>



Part of the [Computer Engineering Commons](#), and the [Other Electrical and Computer Engineering Commons](#)

Keramatnejad, Kamran; Rabiee Golgir, H.; Zhou, Y. S.; Li, D. W.; Huang, X.; and Lu, Yongfeng, "Reducing Graphene-Metal Contact Resistance via Laser Nano-welding" (2017). *Theses, Dissertations, and Student Research from Electrical & Computer Engineering*. 78. <http://digitalcommons.unl.edu/elecengtheses/78>

This Article is brought to you for free and open access by the Electrical & Computer Engineering, Department of at DigitalCommons@University of Nebraska - Lincoln. It has been accepted for inclusion in Theses, Dissertations, and Student Research from Electrical & Computer Engineering by an authorized administrator of DigitalCommons@University of Nebraska - Lincoln.

Authors

Kamran Keramatnejad, H. Rabiee Golgir, Y. S. Zhou, D. W. Li, X. Huang, and Yongfeng Lu



Reducing Graphene-Metal Contact Resistance via Laser Nano-welding

K. Keramatnejad, H. Rabiee Golgir, Y. S. Zhou, D. W. Li, X. Huang, and Y. F. Lu*
Department of Electrical and Computer Engineering, Univ. of Nebraska-Lincoln
Lincoln, Nebraska 68588-0511, United States



University of
Nebraska-Lincoln

E-mail: ylu2@unl.edu

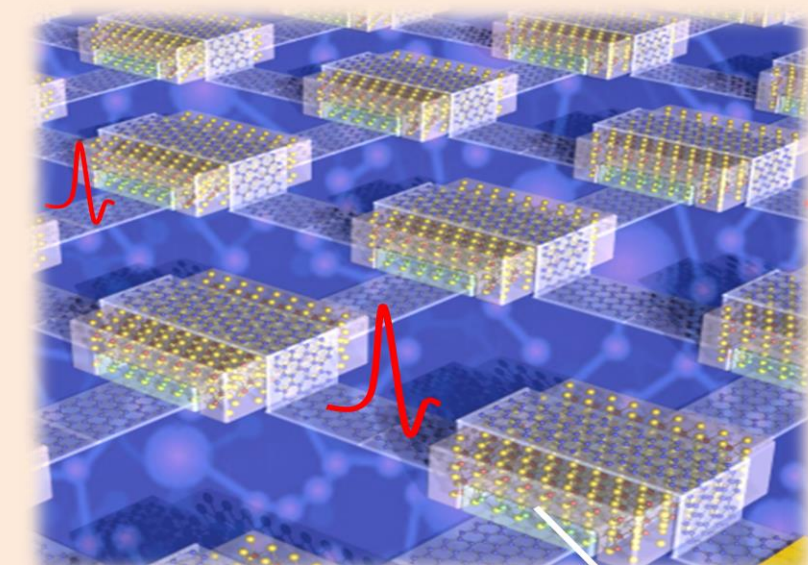
Website: <http://lane.unl.edu>

Laser Assisted
Nano-Engineering Lab

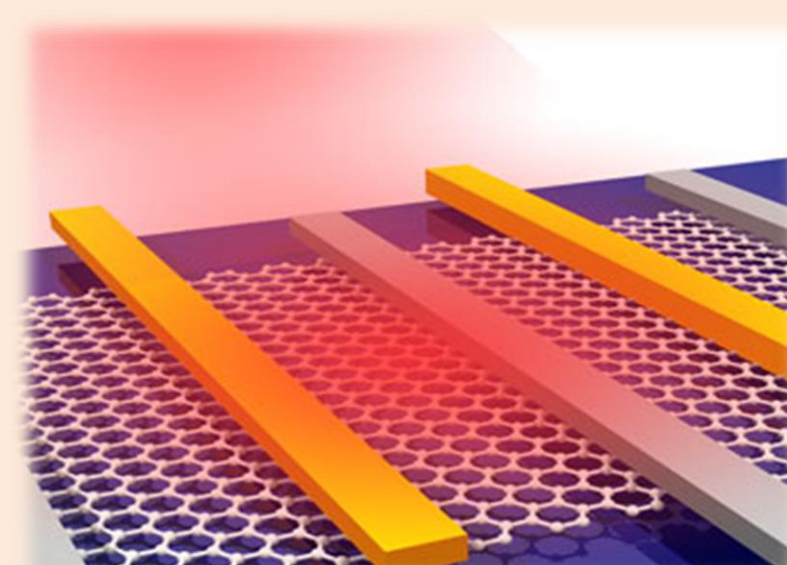
MOTIVATION AND CHALLENGES



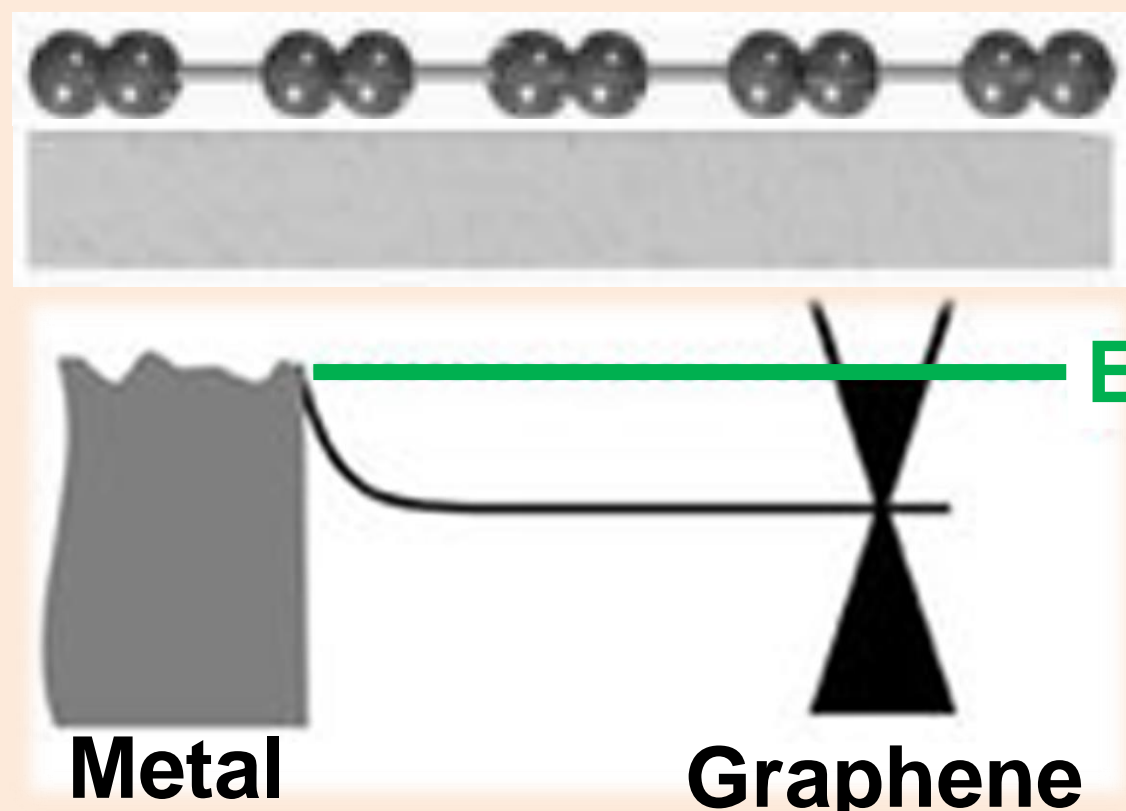
Flexible electronics



Transparent electrodes



Optoelectronics

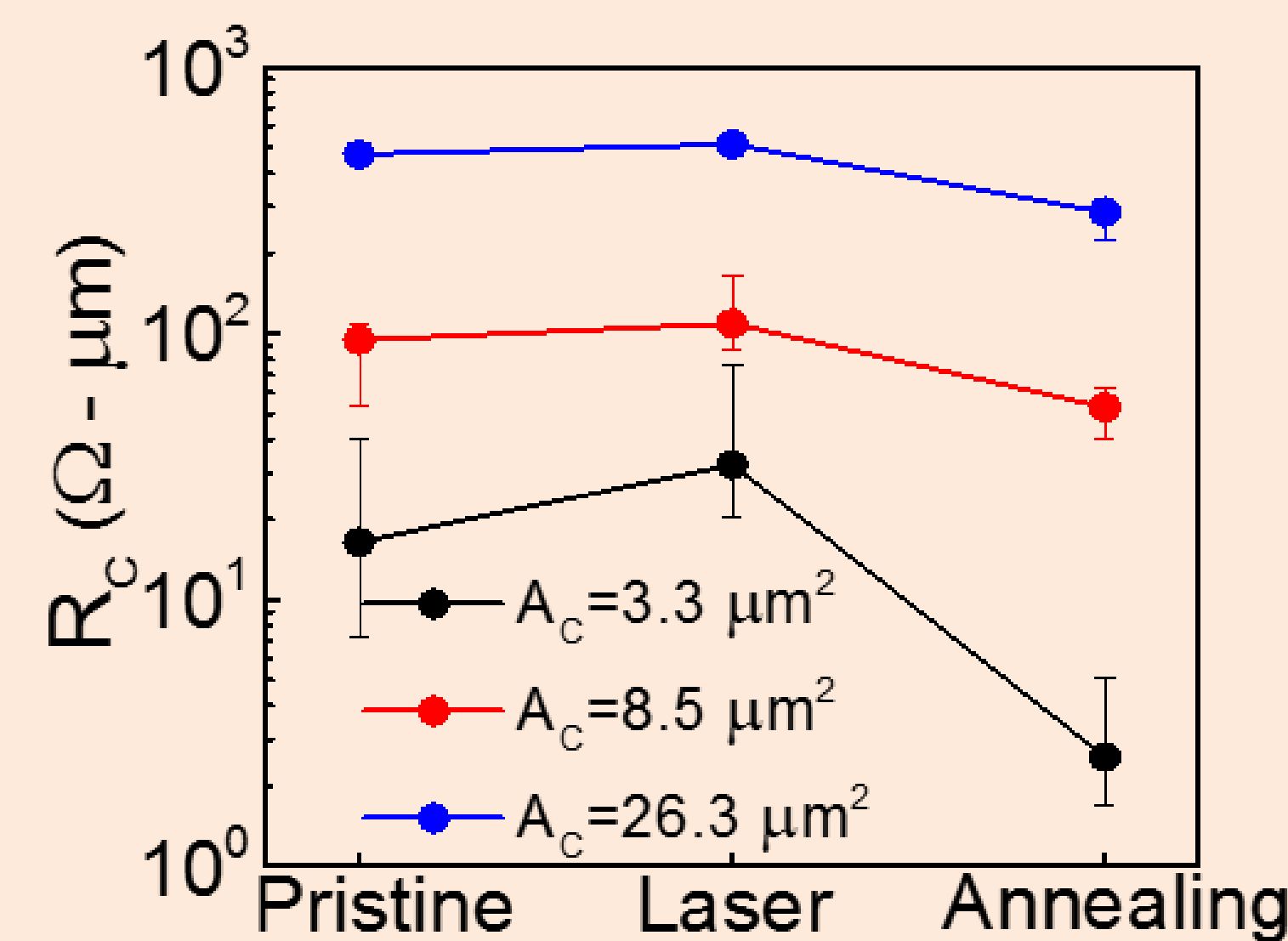


X The large graphene-metal contact resistance is a major limitation for development of graphene electronics.

X graphene behaves as an insulator for out-of-plane carrier transport to metallic contacts.

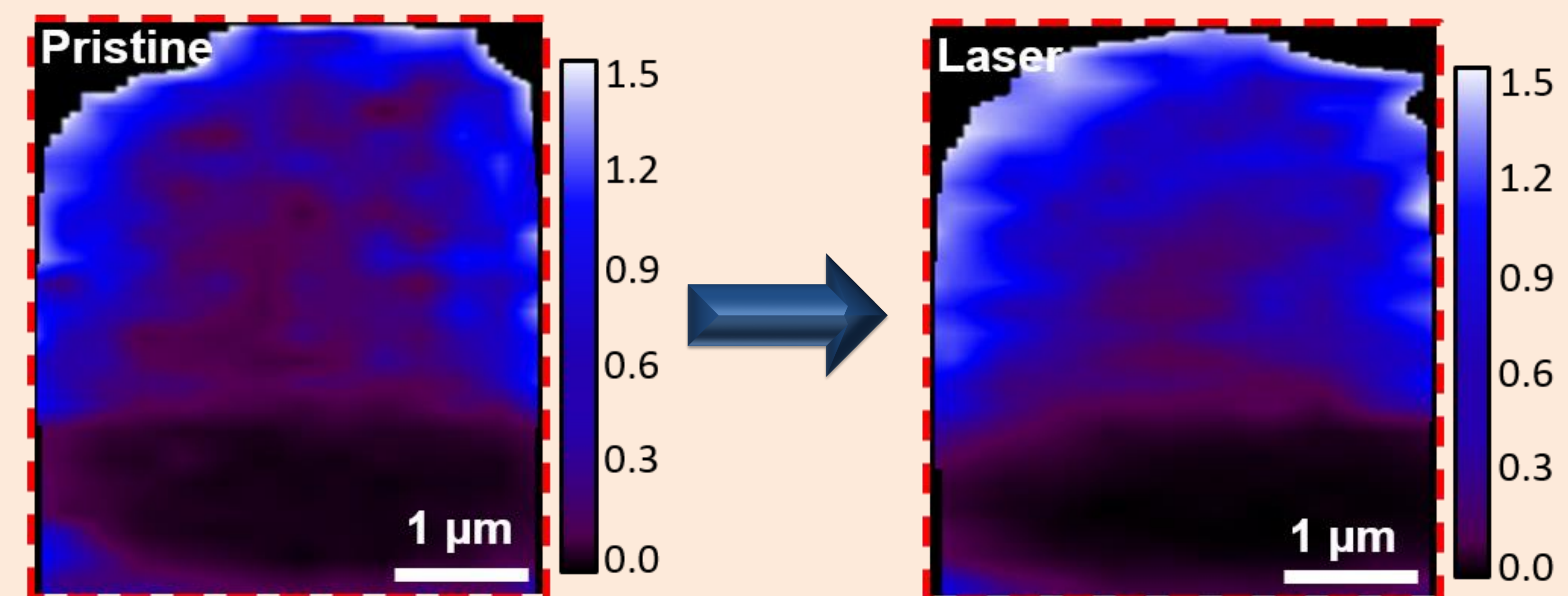
RESULTS AND DISCUSSION

I. Reducing the Contact resistance via laser nano-welding



- Slight increase in R_C for all samples after the laser-irradiation.
- Significant reduction of R_C values after the annealing.
- R_C values as low as $2.57 \Omega \cdot \mu\text{m}$ obtained via laser nano-welding method.

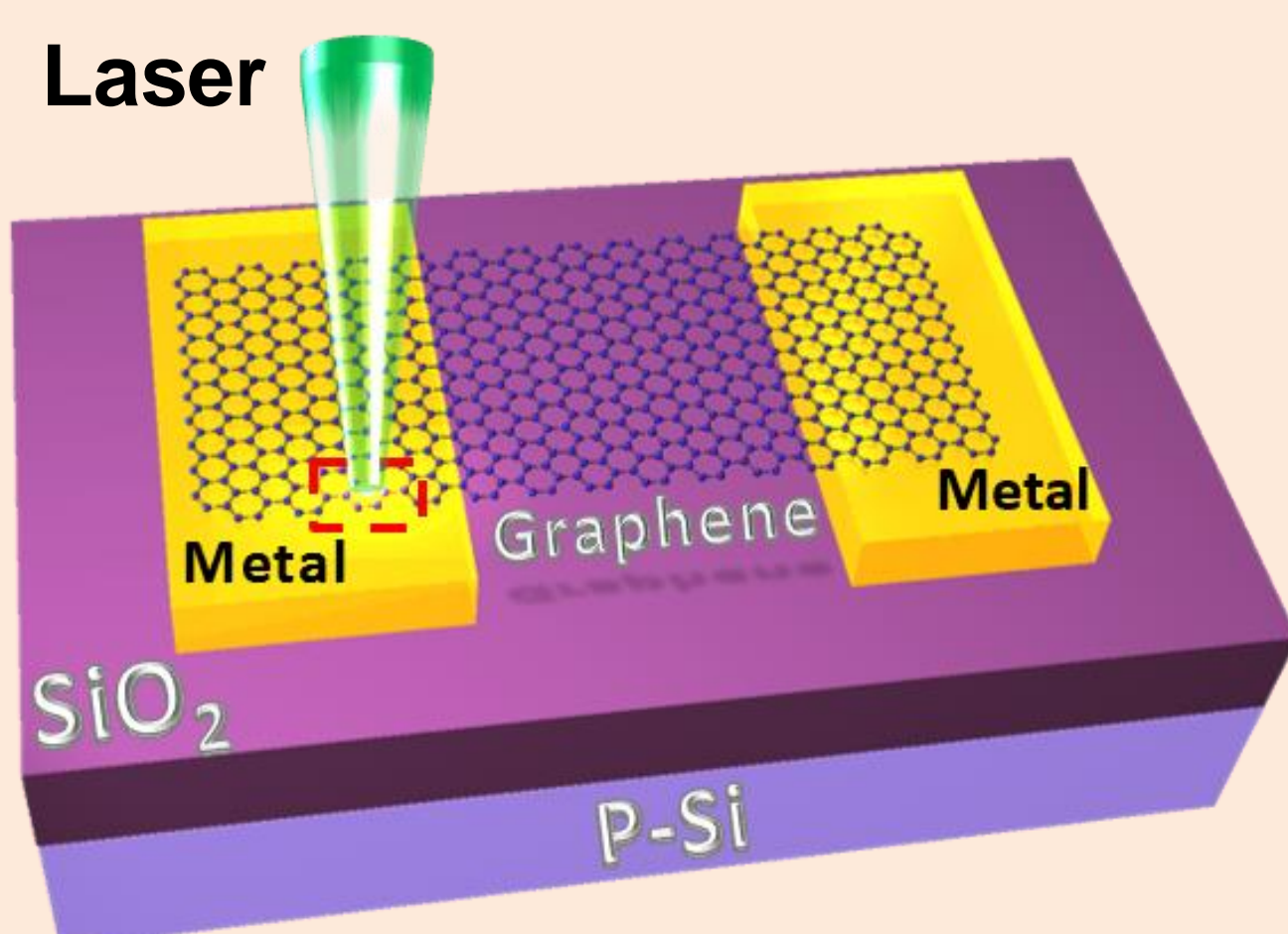
II. Structural characterization using I_D/I_G Raman mapping



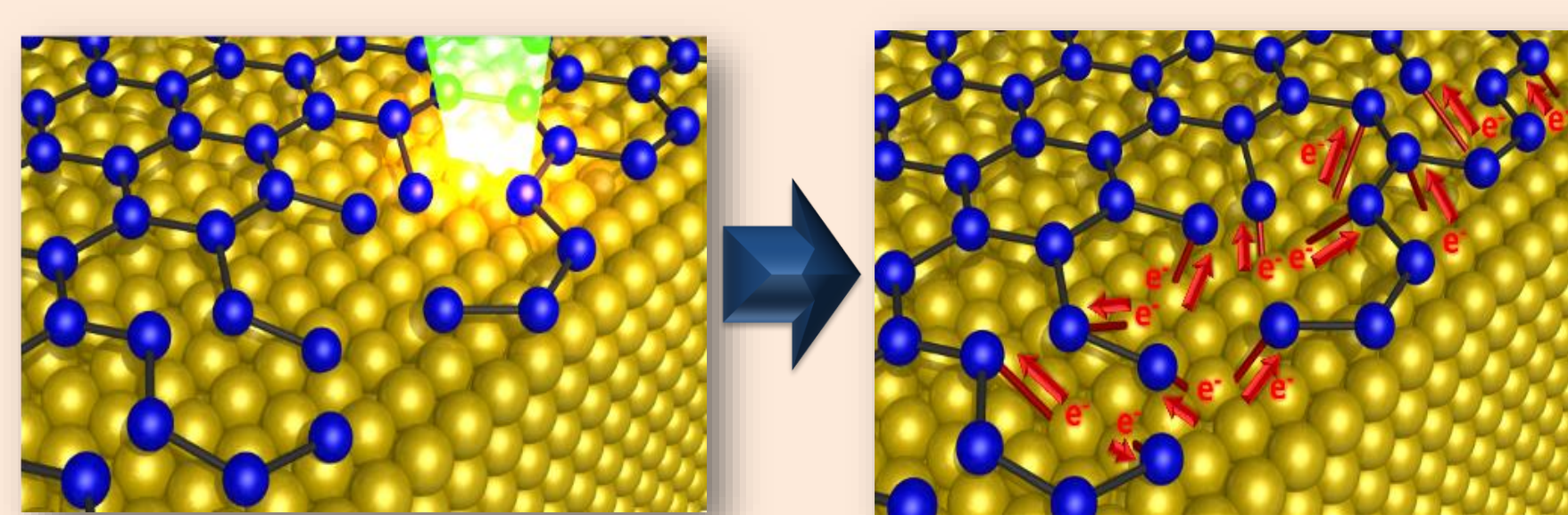
- A rise in the I_D/I_G ratio was observed only at the edges of graphene, where laser irradiation was performed.
- No change was observed at the channel region and the middle of graphene-metal interface.
- Performance degradation was avoided, due to selective mechanism of the laser-irradiation.

PROPOSED SOLUTION

Laser nano-welding of graphene to the metal contacts



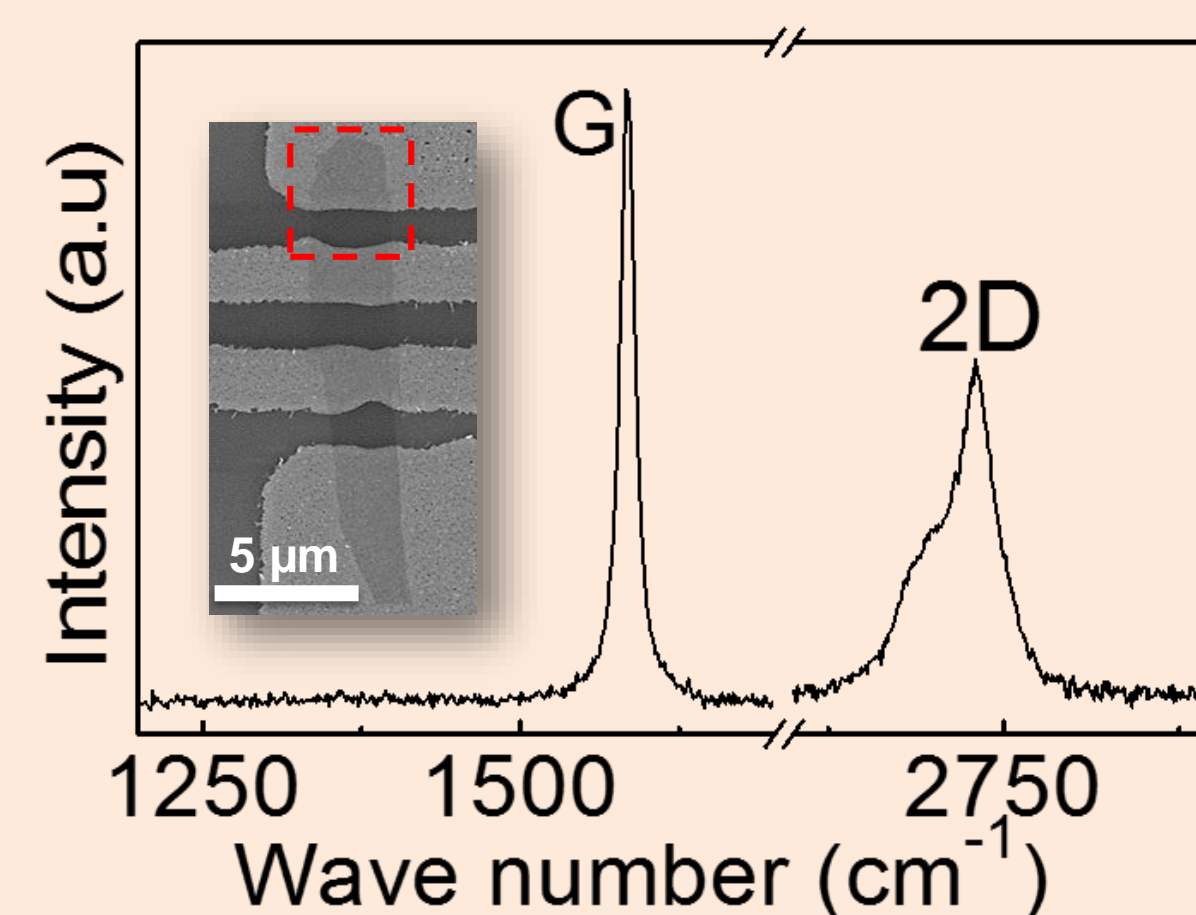
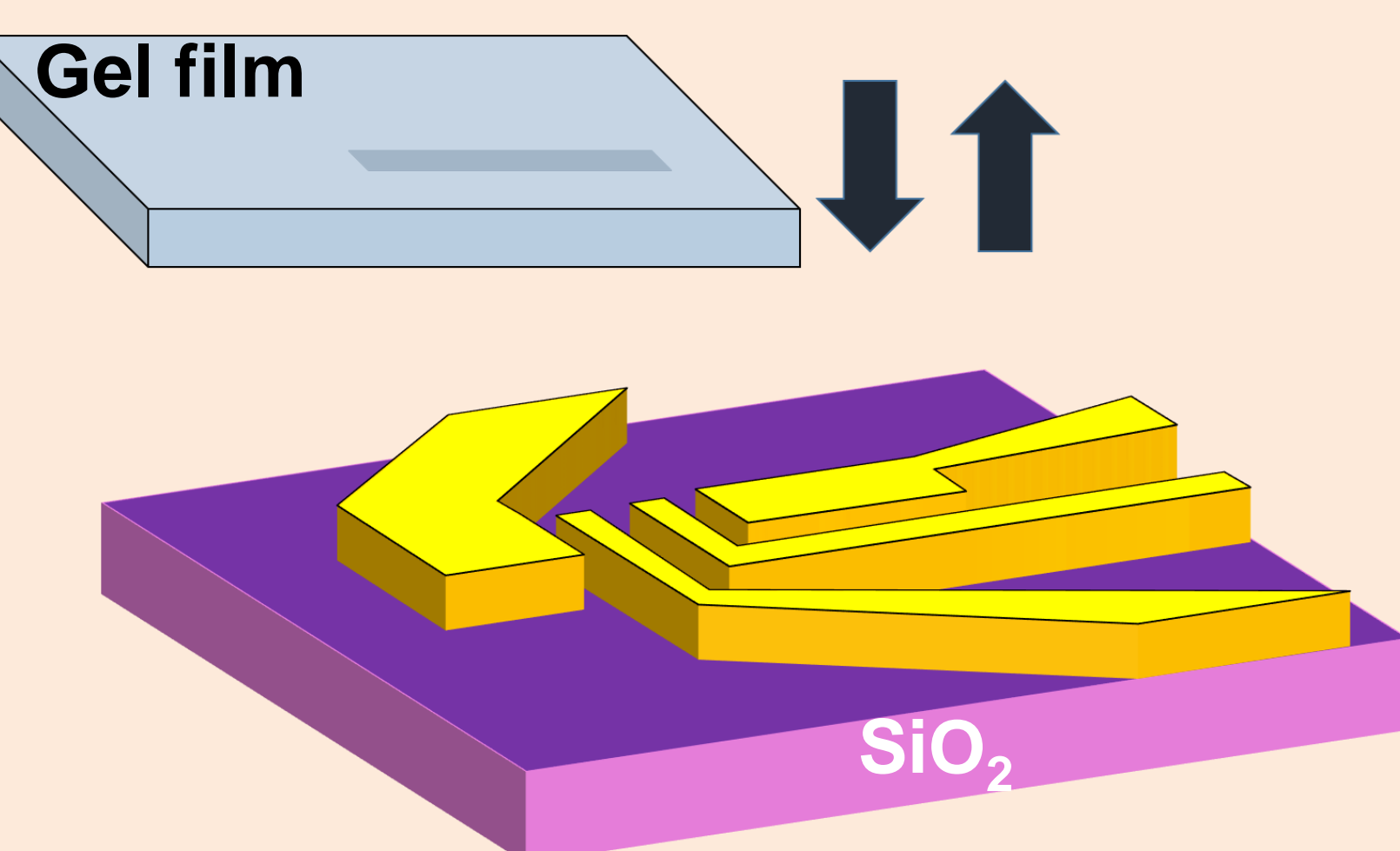
- Laser-induced formation of defects.
- Increase the chemical reactivity of graphene.
- Avoid unwanted damage to channel region.



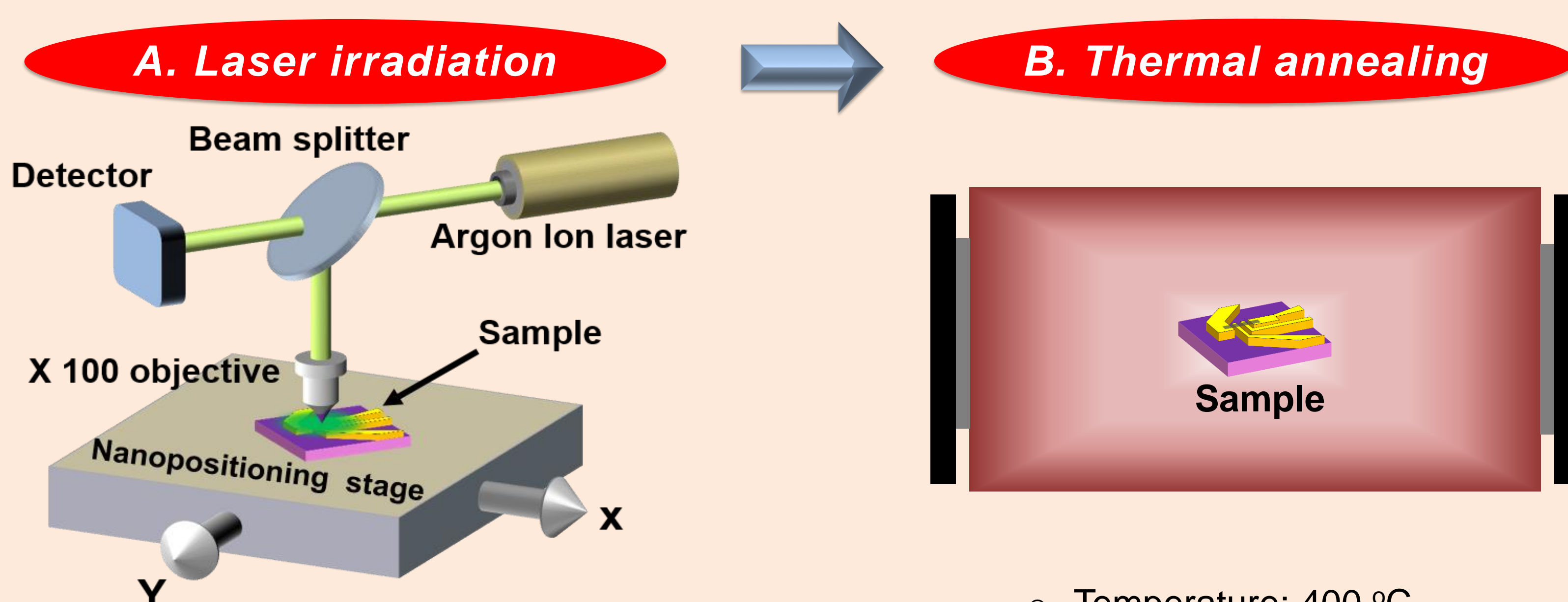
❖ Realization of a strong G-M bonding at laser-induced defects.

METHODS

I. Fabrication of the four-point probe structures



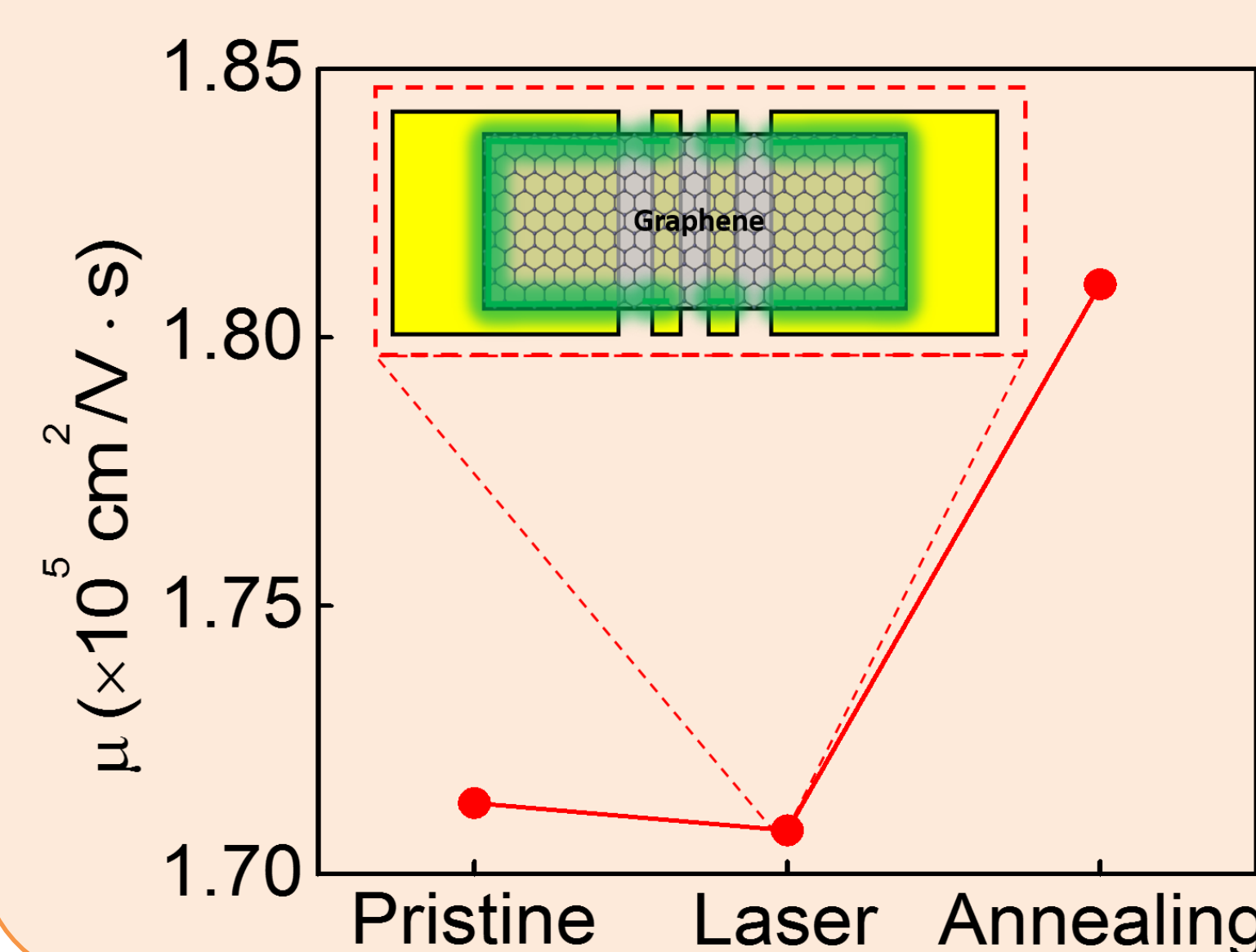
II. Laser nano-welding of graphene



- Wavelength: 514 nm.
- Laser Fluence: $1.6 \times 10^3 \text{ J/cm}^2$.

- Temperature: 400 °C.
- Time: 1 hr.
- Pressure: 1-5 mTorr (Ar purge).

III. Carrier mobility



- Slight reduction in the mobility after the laser irradiation.
- Increased mobility after the thermal annealing.
- Improved carrier injection efficiency, due to the bonding formation at the edges of graphene.

CONCLUSIONS

- ✔ Laser nano-welding was developed and led to R_C reductions of up to **84%**.
- ✔ Localized laser irradiation at the edges of graphene led to the formation of chemically active **point defects**.
- ✔ Precise structural modifications and formation of **G-M bonding** led to improved carrier efficiency in graphene devices.

ACKNOWLEDGEMENTS

This research work was financially supported by the National Science Foundation (CMMI 1265122), Nebraska Materials Research Science and Engineering Center (MRSEC, DMR-1420645), and Nebraska Center for Energy Sciences Research (NCESR).

